MSKSEMI 美森科













ESD

S

TSS

MOV

GDT

PLED

2CL74A-MS/2CL75A-MS

Product specification





Features

- Super small size
- High reliability
- High speed switching

Typical Applications

Mechanical Data

Package: DO-210

Epoxy meets UL 94 V-0 flammability rating

• Terminals: Pure tin plated leads, solderable per

J-STD-002 and JESD22-B102

Polarity: Color band denotes the cathode end

Reference News

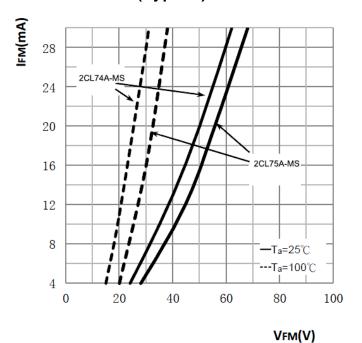
PACKAGE OUTLINE	Pin Configuration	Mark	king
		T74A	T75A
		2CL74A-MS	2CL75A-MS

Maximum Ratings (Ta=25℃ Unless otherwise specified)

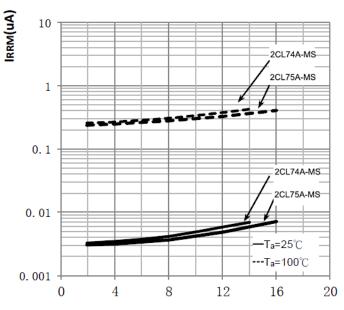
PARAMETER	SYMBOL	UNIT	Conditions	2CL74A-MS	2CL75A-MS
Device marking code				T74A	T75A
Repetitive Peak Reverse Voltage	V_{RRM}	KV		14	16
Non-Repetitive Peak Reverse Voltage	V_{RSM}	KV		17	20
Average Forward Current	I _{F(AV)}	mA	60Hz half-sine wave, Resistance load, Ta=25°C		5
Non-Repetitive Forward Surge Current	I _{FSM}	Α	60Hz half-sine wave,1 cycle, Ta = 25℃	0.5	
Peak Forward Voltage	V_{FM}	V	I _{FM} =10mA	51	60
	IRRM	μА	V _{RM} = V _{RRM} , Ta=25°C		2
Peak Reverse Current			V _{RM} = V _{RRM} , Ta=100°C		5
Reverse Recovery time	t _{rr}	μs	I _F =2mA,I _{RM} =4mA,I _{RR} =1mA	0	.08
Operating Ambient Temperature	Ta	°C		-40 ~ +100	
Storage Temperature	T _{stg}	°C		-40 -	~ +120
Virtual Junction Temperature	T _(vj)	°C		120	



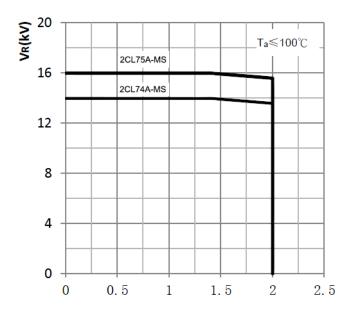
Characteristics(Typical)



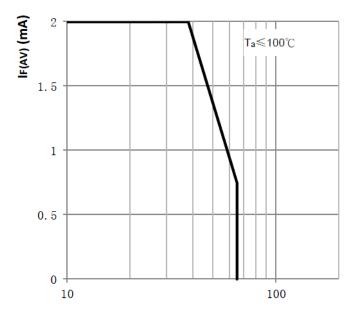




VRM (kV) Figure 2. Reverse characteristics



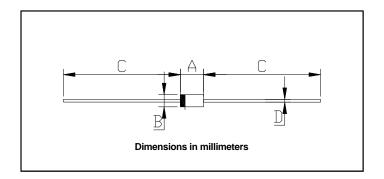
IF(AV) (mA) Figure 3. VR-IF(AV) Curve



fh(kHz) Figure 4. IF(AV)-fh Curve



Outline Dimensions



DO-210					
Dim	Min	Max			
Α	9.8	10.2			
В	2.3	2.7			
С	26	/			
D	0.47	0.53			

Order information

Orderable Device	Package	Packing Option
2CL74A-MS/2CL75A-MS	DO-210	5000PCS



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